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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/705,881	11/13/2003	Yoshimasa Nagakura	032105	6093
38834 7	7590 09/30/2005		EXAM	INER
	N, HATTORI, DANIE	SCHILLINGE	R, LAURA M	
1250 CONNECTICUT AVENUE, NW SUITE 700 WASHINGTON, DC 20036			ART UNIT	PAPER NUMBER
			2813	

DATE MAILED: 09/30/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
Office Action Comments	10/705,881	NAGAKURA ET AL.				
Office Action Summary	Examiner	Art Unit				
	Laura M. Schillinger	2813				
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).						
Status						
1)⊠ Responsive to communication(s) filed on 14 Ju	ılv 2005.					
	action is non-final.					
·—	s application is in condition for allowance except for formal matters, prosecution as to the merits is					
•	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4)⊠ Claim(s) <u>1-36</u> is/are pending in the application.						
4a) Of the above claim(s) <u>5-12,14-16,18-20,22-24,26-28,30-32 and 34-36</u> is/are withdrawn from consideration.						
5) Claim(s) is/are allowed.						
6)⊠ Claim(s) <u>1-4,13,17,21,25,29 and 33</u> is/are rejected.						
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/or	8) Claim(s) are subject to restriction and/or election requirement.					
Application Papers		•				
9) The specification is objected to by the Examiner.						
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.						
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).						
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).						
11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. § 119						
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 11/13/03.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:					

DETAILED ACTION

Election/Restrictions

Claims 5-12, 14-16, 18-20, 22-24, 26-28, 30-32, 34-36 are withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected claims, there being no allowable generic or linking claim. Election was made without traverse in the reply filed on 7/14/05.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

Claims 1-4, 13, 17, 21, 25, 29, and 33 are rejected under 35 U.S.C. 102(a) as being anticipated by Japanese Publication 2001338976).

1. A method for fabricating a semiconductor device comprising:

the step of depositing an insulation film with a first pressure set in a deposition chamber; the pressure adjusting step of decreasing a pressure in the deposition chamber from a first pressure to a second pressure which lower than the first pressure; and the step of further depositing the insulation film with the second pressure set in the deposition chamber (Abstract, Solution).

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- 2. A method for fabricating a semiconductor device according to claim wherein the pressure adjusting step, pressure the deposition chamber is gradually decreased from the first pressure the second pressure while an atmosphere in the deposition chamber is being replaced by an inert atmosphere [0041].
- 3. A method for fabricating a according to claim 1, wherein in the pressure adjusting step, semiconductor device pressure in the deposition chamber is gradually decreased at a rate smaller than 40 Torr/sec [0041-drawing 18].
- 4. A method for fabricating a semiconductor device according claim 3, wherein in the pressure adjusting step, pressure in the deposition chamber is gradually decreased at a 5 40 Torr/sec [0041-drawing 18].
- 13. A method for fabricating a semiconductor device according to claim which further comprises, before the step of depositing the insulation film, the step of forming a gate electrode of a transistor on a semiconductor substrate; and in which in the step of depositing the insulation film, the insulation film is deposited so as to cover the gate electrode[0037].
- 17. A method for fabricating a semiconductor device according to claim 1, which further comprises, before the step of depositing the insulation film, step of forming an interconnection layer above the semiconductor substrate [0037]; and

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in which in the step of depositing the insulation film, the insulation film deposited so as to cover

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the interconnection layer[0038].

21. A method for fabricating a semiconductor device according to claim 1, wherein

the first pressure is 400 - 600 Torr [0040]; and

the second pressure is 200 - 400 Torr [0041].

25. A method for fabricating a semiconductor device according to claim wherein the step of

depositing the insulation film, insulation film deposited by thermal chemical vapor deposition

(Abstract, Solution).

29. A method for fabricating a semiconductor device according to claim 1, wherein the insulation

film is a BPSG film, a BSG film, a PSG film or an USG film[0040].

33. A method for fabricating a semiconductor device according to claim 1, further comprising,

after the step of further depositing the insulation film, the step of polishing the surface of the

insulation film [0041].

Conclusion

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Laura M. Schillinger whose telephone number is (571) 272-1697. The examiner can normally be reached on M-T, R-F 7:00-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl W. Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

O9/27/05 Melely

Laura M Schillinger Primary Examiner Art Unit 2813